Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
u	594	"257"/\$:ccls, and mold with (protrus\$4 project\$4) and (chip die ic) and (substrate board carrier)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 10:17
L2	343	"257"/\$.ccls. and mold with (protrus\$4 project\$4) and (chip die ic) and (substrate board carrier) with (open\$4 via hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 10:28
ß	134	"438"/\$.ccls. and mold with (protrus\$4 project\$4) and (chip die ic) and (substrate board carrier) with (open\$4 via hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 10:32
L4	57	"361"/\$.ccls. and mold with (protrus\$4 project\$4) and (chip die ic) and (substrate board carrier) with (open\$4 via hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON .	2005/09/19 10:34
L5	78	"29"/\$.ccls. and mold with (protrus\$4 project\$4) and (chip die ic) and (substrate board carrier) with (open\$4 via hole)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 10:34